

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YASUSHI FUJIMURA	08/01/2016
YUTAKA MORIYAMA	08/02/2016
MASARU TAKECHI	08/02/2016
TAKEHIKO KIKUCHI	08/01/2016
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<b>State/Country:</b>	JAPAN
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15222483
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<b>NAME OF SUBMITTER:</b>	TAMATANE J. AGA
<b>SIGNATURE:</b>	/Tamatane J. Aga/
<b>DATE SIGNED:</b>	08/15/2016
<b>Total Attachments: 2</b>	
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**ASSIGNMENT**

Whereas, I/we,

<u>Name</u>	<u>Address</u>
1) <b>Yasushi FUJIMURA</b>	c/o Yokohama Works of Sumitomo Electric Industries, Ltd., 1, Taya-cho, Sakae-ku, Yokohama-shi, Kanagawa 244-8588 Japan
2) <b>Yutaka MORIYAMA</b>	c/o Yokohama Works of Sumitomo Electric Industries, Ltd., 1, Taya-cho, Sakae-ku, Yokohama-shi, Kanagawa 244-8588 Japan
3) <b>Masaru TAKECHI</b>	c/o Yokohama Works of Sumitomo Electric Industries, Ltd., 1, Taya-cho, Sakae-ku, Yokohama-shi, Kanagawa 244-8588 Japan
4) <b>Takehiko KIKUCHI</b>	c/o Yokohama Works of Sumitomo Electric Industries, Ltd., 1, Taya-cho, Sakae-ku, Yokohama-shi, Kanagawa 244-8588 Japan

hereinafter called assignor(s), have invented certain improvements in  
**OPTICAL MODULE HAVING MULTI-MODE COUPLER FORMED ON SEMICONDUCTOR SUBSTRATE**

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on July 28, 2016, Serial No. 15/222 483; and

Whereas

SUMITOMO ELECTRIC INDUSTRIES, LTD.  
5-33, Kitahama 4-chome, Chuo-ku,  
Osaka-shi, Osaka 541-0041 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

	<u>INVENTORS</u>	<u>DATE SIGNED</u>
1) :	<u>Yasushi Fujimura</u>	<u>August 1, 2016</u>
Name :	Yasushi FUJIMURA	
2) :	<u>Yutaka Moriyama</u>	<u>August 2, 2016</u>
Name :	Yutaka MORIYAMA	
3) :	<u>Masaru Takechi</u>	<u>August 2, 2016</u>
Name :	Masaru TAKECHI	

4) :

Name :

Takehiko Kikuchi

Takehiko KIKUCHI

August 1, 2016